

Low Ohm (Metal Strip) Chip Resistor- LRP Series

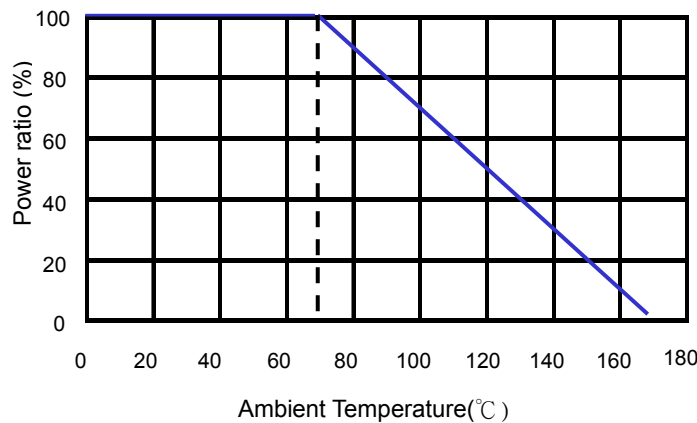
■ Features

- High power rating up to 3 Watts
- Low TCR down to ± 50 PPM/ $^{\circ}\text{C}$
- Resistance values from 10m to 100m ohm
- Customized resistance available

■ Applications

- NB (for Power Management)
- MB (for Power Management)
- SWPS (DC-DC Converter, Charger, Adaptor)
- Monitor (for Power Management)

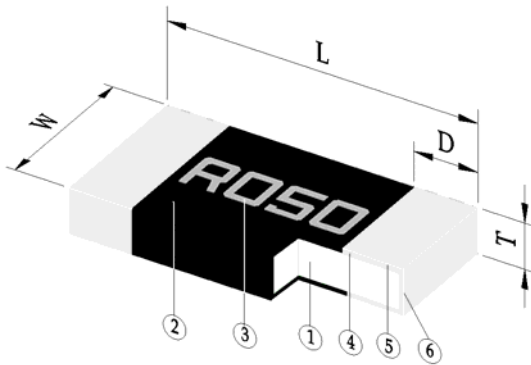
■ Derating Curve



■ Part Numbering

LRP	12	F	T	D	S	R015	
Product Type	Dimensions (L×W)	Resistance Tolerance	Packaging Code	TCR (PPM/ $^{\circ}\text{C}$)	Power Rating	Resistance	Marking
	12: 2512	D: $\pm 0.5\%$ F: $\pm 1\%$ J: $\pm 5\%$	T: Taping Reel	D: ± 50 W: ± 75	R: 3W S: 2W T: 1W	R015: 0.015Ω R050: 0.05Ω	N: No Marking

Construction



① Alloy Plate	④ Internal Electrode (Cu)
② Overcoat (Epoxy)	⑤ Barrier Layer (Ni)
③ Marking	⑥ Solder Plating (Sn)

Dimensions

Type	Size (Inch)	L (mm)	W (mm)	T (mm)	D (mm)
LRP12	2512	6.40±0.25	3.20±0.25	0.70±0.20	0.90±0.30

Electrical Specifications

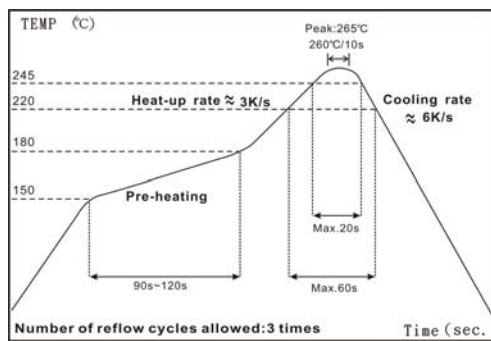
For MnCu Material

Type	Item	Power Rating at 70°C	Operating Temp. Range	Resistance Range (mΩ)			TCR (PPM/°C)
				±0.5%	±1%	±5%	
LRP12 (2512)		1W, 2W, 3W	-55 ~ +170°C	10 – 100			±75
				15 – 100			±50

Operating Current = $\sqrt{P/R}$, Operating Voltage = $\sqrt{P \cdot R}$

■ Viking is capable of manufacturing the optional spec based on customer's requirement.

Soldering Condition(Reflow soldering only)



IR Reflow Soldering

- (1) Time of IR reflow soldering at maximum temperature point 260°C : 10s
- (2) Time of soldering iron at maximum temperature point 410°C : 5s

■ Environmental Characteristics

Item	Requirement	Test Method
Temperature Coefficient of Resistance (T.C.R.)	As Spec.	IEC60115-1 4.8 JIS-C-5201-1 4.8 -55°C~+125°C, 25°C is the reference temperature
Short Time Overload	±1.0%	IEC60115-1 4.13 JIS-C-5201-1 4.13 5*rated power for 5 seconds
Insulation Resistance	>100MΩ	IEC60115-1 4.6 JIS-C-5201-1 4.13 100V DC for 1 minute
Endurance	±1.0%	IEC60115-1 4.25 JIS-C-5201-1 4.25.1 70±2°C, rated power for 1000 hrs with 1.5 hrs "ON" and 0.5 hrs "OFF"
Biased Humidity	±1.0%	MIL-STD-202 Method 103 1000 hrs 85°C/85%RH 10% of operating power
Dry Heat	±1.0%	IEC60115-1 4.23.2 JIS-C-5201-1 4.23.2 at +170°C for 1000 hrs
Bending Strength	±1.0%	JIS-C-5201-1 4.33 IEC-60115-1 4.33 Bending width 2mm once for 5 seconds
Solderability	95% min. coverage	JIS-C-5201-1 4.17 IEC-60115-1 4.17 245±5°C for 3 seconds
Resistance to Soldering Heat	±0.5%	JIS-C-5201-1 4.18 IEC-60115-1 4.18 260±5°C for 10 seconds
Rapid Change of Temperature	±1.0%	JIS-C-5201-1 4.19 IEC-60115-1 4.19 -55°C to +155°C, 5 cycles
Low Temperature Storage	±1.0%	IEC60115-1 4.23.4 JIS-C-5201-1 4.23.4 at -55°C for 1000 hrs

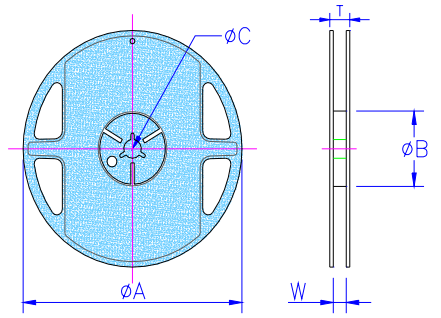
RCWV(Rated continuous working voltage)= $\sqrt{P \cdot R}$ or Max. Operating voltage whichever is lower

■ Storage Temperature: 25±3°C; Humidity < 80%RH

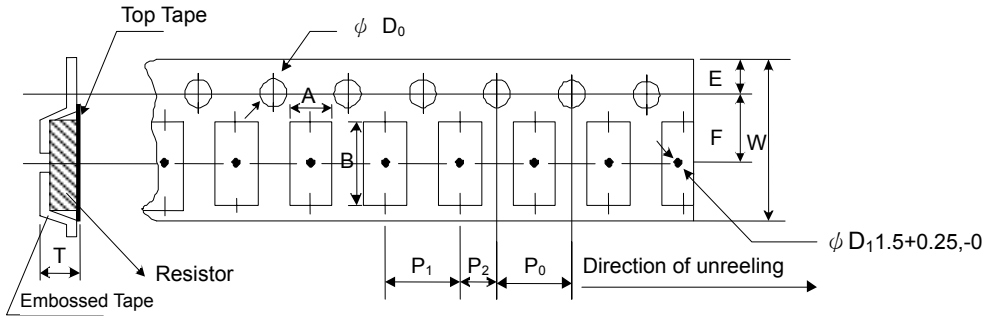
■Packaging

Reel Specifications & Packaging Quantity

Type	Packaging Quantity	Tape Width	Reel Diameter	ΦA (mm)	ΦB (mm)	ΦC (mm)	W (mm)	T (mm)	
LRP12	Embossed	4K	12mm	7 inch	178.5+/-1.5	60±1.0	13.0±0.5	13.0±1.0	15.5±0.5

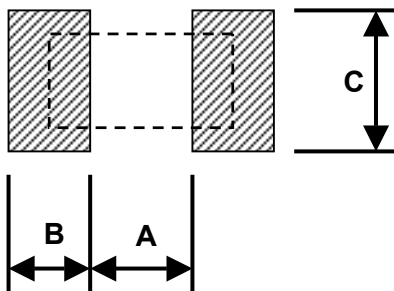


Embossed Plastic Tape Specifications



Type	A (mm)	B (mm)	W (mm)	E (mm)	F (mm)	P ₀ (mm)	P ₁ (mm)	P ₂ (mm)	ΦD ₀ (mm)	T (mm)
LRP12	3.50±0.10	6.70±0.10	12.0±0.30	1.75±0.10	5.5±0.05	4.00±0.10	4.00±0.10	2.00±0.05	1.50+0.1, -0	1.20+0

■Recommend Land Pattern



Type	A (mm)	B (mm)	C (mm)
LRP12	4.00	2.00	3.50

* FR4 copper board, 100 μ m of copper pad thickness

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version A	Apr 30,2015	-	- First issue of this specification
Version A1	Jul 30,2015	-	- Add 0.5% Resistance Range